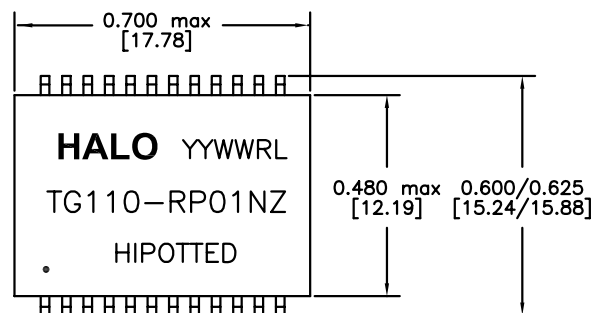
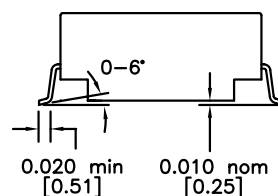
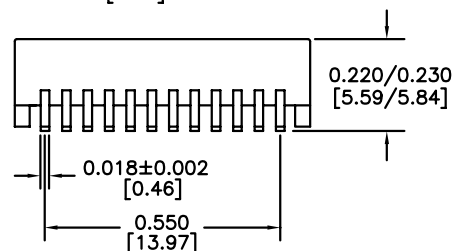
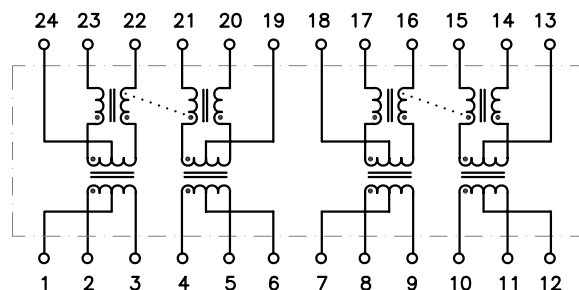




0.050
[1.27]



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



CHIP SIDE



PART NO. : TG110-RP01NZRL

DUAL-PORT FAST OR SINGLE GIGABIT ETHERNET
COMPLIANT WITH IEEE802.3af REQUIREMENTS

350mA DC CURRENT CARRYING CAPACITY
ON LINE SIDE FOR PoE APPLICATIONS

RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

OPERATING TEMPERATURE 0/+70°C

ELECTRICAL SPECIFICATIONS @25° C

URNS RATIO	1CT:1CT ±2%
OCL (100KHz,0.1Vrms,8mA)	350µH min
DCR (CHIP SIDE)	0.9Ω max
INSERTION LOSS	
1-100MHz	-1.1dB max
RETURN LOSS	
1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CROSSTALK	
1-100MHz	-38dB typ
CMR	
1-100MHz	-38dB typ
ISOLATION	1,500Vrms



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE	SIGNATURES	DATE	REV.	DESC.	DATE
FOR	FAST/GIGABIT ETHERNET, PoE	DRAWN PETER LU	11/22/05	A	FIRST ISSUE	11/22/05
PART NO.	TG110-RP01NZRL	CHECKED LEI KEONG	2/15/06	B	PROD. RELEASE	2/15/06
SCALE	NONE	APPROVED PETER LU	2/15/06			
PAGE	1 OF 1	FILE RP01NZRL.DWG				